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Space product assurance - Qualification and Procurement of printed circuit boards;  
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## Table of contents

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<b>European Foreword</b> .....	<b>11</b>
<b>Introduction</b> .....	<b>12</b>
<b>1 Scope</b> .....	<b>13</b>
<b>2 Normative references</b> .....	<b>14</b>
<b>3 Terms, definitions and abbreviated terms</b> .....	<b>16</b>
3.1 Terms from other standards.....	16
3.2 Terms specific to the present standard .....	17
3.3 Abbreviated terms.....	24
3.4 Nomenclature .....	26
<b>4 Principles</b> .....	<b>28</b>
4.1 General.....	28
4.2 Roles .....	28
4.3 List of conditions.....	28
4.4 References to acceptance criteria.....	28
<b>5 QA for qualification</b> .....	<b>29</b>
5.1 Qualified PCBs .....	29
5.2 Special PCB technology .....	29
5.3 Qualification process .....	30
5.4 Request for qualification .....	30
5.5 Quality standards.....	31
5.6 Description of qualification vehicle .....	31
5.7 Evaluation.....	32
5.8 Audit .....	33
5.9 Qualification test programme .....	34
5.10 PID .....	35
5.11 Qualification approval .....	35
5.12 Process change.....	36
5.13 QA report.....	36
5.14 Qualification renewal .....	36

5.15	Nonconformances during qualification renewal .....	37
<b>6</b>	<b>QA for manufacture and procurement.....</b>	<b>39</b>
6.1	Overview .....	39
6.2	Procurement process.....	39
6.2.1	Overview.....	39
6.2.2	Procurement specification .....	40
6.2.3	Quotation .....	40
6.2.4	Purchase order .....	41
6.2.5	Design review (DR).....	41
6.2.6	MRR .....	41
6.3	Final and in-process inspection.....	42
6.4	Quality records for manufacture and procurement .....	43
6.5	Control of materials and chemistry.....	44
6.6	Cleanliness of PCB processes.....	45
6.6.1	Overview.....	45
6.6.2	Cleanliness control.....	46
6.7	Traceability .....	48
6.8	Operator and inspector training.....	49
6.9	Repair of bare PCBs.....	49
6.9.1	Overview .....	49
6.9.2	General .....	49
6.10	Packaging.....	51
6.11	Storage and baking of PCB and coupons .....	52
6.12	Shelf-life and relife testing.....	52
6.13	QA for PCB procurement in space projects.....	53
<b>7</b>	<b>Test and inspection for qualification .....</b>	<b>56</b>
7.1	Overview .....	56
7.2	Test selection for qualification activities .....	58
7.3	Initial qualification of PCB manufacturer .....	62
7.4	Initial qualification of PCB technology .....	62
7.5	Qualification renewal .....	62
7.6	Delta qualification .....	62
7.7	Project qualification and RFA.....	63
7.7.1	Overview.....	63
7.7.2	Requirements for project qualification and RFA .....	63
<b>8</b>	<b>Test and inspection for procurement .....</b>	<b>67</b>

8.1	Outgoing inspection on PCB .....	67
8.2	Outgoing inspection on coupons .....	68
8.2.1	Overview .....	68
8.2.2	Configuration of coupons for plated holes .....	71
8.2.3	Configuration of dedicated coupons .....	73
8.2.4	Evaluation of coupons .....	74
8.2.5	Delivery of coupons, microsections and spare coupons .....	76
8.3	Reporting of outgoing inspection and delivery .....	76
8.4	Incoming inspection by procurement authority .....	77
8.5	FAI on PCB by microsectioning .....	78
<b>9</b>	<b>Test descriptions .....</b>	<b>80</b>
9.1	Overview .....	80
9.2	Additional tests .....	80
9.2.1	Cleanliness .....	80
9.2.2	Bake-out .....	80
9.2.3	Plated copper tensile strength and elongation .....	81
9.2.4	Steam ageing .....	81
9.3	Group 1 – Visual inspection and non-destructive tests .....	82
9.3.1	Visual inspection - general .....	82
9.3.2	Visual inspection for qualitative aspects .....	82
9.3.3	Visual inspection for dimensional verification .....	82
9.3.4	Impedance test .....	86
9.3.5	Dielectric constant and loss tangent .....	86
9.3.6	Cleanliness .....	86
9.3.7	High resistance electrical test .....	87
9.4	Group 2 - Miscellaneous tests .....	89
9.4.1	Overview .....	89
9.4.2	Peel strength .....	90
9.4.3	Flexural fatigue .....	90
9.4.4	Bending test .....	92
9.4.5	Coating adhesion – tape test .....	93
9.4.6	Analysis of tin-lead coating .....	93
9.4.7	Outgassing .....	94
9.4.8	Thermal analysis .....	94
9.4.9	Flammability .....	95
9.4.10	Offgassing .....	95
9.4.11	Solderability .....	95

9.5	Group 3 – Thermal stress and as-received .....	100
9.5.1	Overview .....	100
9.5.2	Microsectioning .....	100
9.5.3	Solder bath float.....	105
9.5.4	Rework simulation.....	105
9.5.5	Interconnect stress test (IST) .....	107
9.6	Group 4 – Assembly and life test - extended.....	113
9.6.1	Overview .....	113
9.6.2	Test flow for group 4 .....	114
9.6.3	Insulation resistance .....	115
9.6.4	Dielectric withstanding voltage (DWV).....	116
9.7	Group 5 – ECM tests .....	117
9.7.1	Overview .....	117
9.7.2	Temperature, Humidity, Bias (THB) .....	118
9.7.3	Conductive Anodic Filament (CAF) .....	123
9.8	Group 6 – Assembly and life test - short .....	128
9.8.1	Overview .....	128
9.8.2	Test flow for group 6 .....	128
9.8.3	Reflow simulation .....	129
9.8.4	Thermal cycling.....	129
<b>10</b>	<b>Acceptance criteria .....</b>	<b>131</b>
10.1	Overview .....	131
10.2	Inspection by microsectioning for dimensional verification .....	131
10.3	Inspection by microsectioning for qualitative aspects.....	153
10.4	Visual inspection.....	185
10.5	Visual inspection of sculptured flex PCB.....	207
10.6	Additional requirement to the tables.....	230
10.6.1	Annular ring.....	230
10.6.2	Pad lift and associated laminate cracks.....	231
10.6.3	Miscellaneous .....	232
	<b>Annex A (normative) Qualification letter – DRD .....</b>	<b>235</b>
	<b>Annex B (normative) CoC – DRD .....</b>	<b>236</b>
	<b>Annex C (normative) Qualification test report – DRD .....</b>	<b>250</b>
	<b>Annex D (normative) Process Identification Document (PID) for PCB manufacturing – DRD.....</b>	<b>251</b>

<b>Annex E (normative) Process change notice (PCN) – DRD .....</b>	<b>253</b>
<b>Annex F (normative) QA report – DRD .....</b>	<b>255</b>
<b>Annex G (normative) PCB approval sheet – DRD .....</b>	<b>256</b>
<b>Annex H (informative) Example of plated-through hole microsection .....</b>	<b>261</b>
<b>Annex I (informative) Cleanliness requirements for laminate and prepreg.....</b>	<b>262</b>
<b>Bibliography.....</b>	<b>265</b>

## **Figures**

Figure 7-1 Test flow for qualification .....	57
Figure 8-1 flow for preparation, test and inspection of procurement coupons .....	71
Figure 8-2 Example of placement of coupons and PCB in usable area of manufacturing panel .....	72
Figure 8-3 Example of vias manufactured at different plating and drilling sequences .....	73
Figure 8-4: Example of target quality of microsection of rigid-flex interface with UV fluorescent resin and polarised light .....	76
Figure 9-1 Conductor width (w) measured at the foot as seen in a cross section.....	84
Figure 9-2: Warp .....	85
Figure 9-3: Twist.....	86
Figure 9-4: Horizontal adjacency on layer Ln and vertical adjacency on the layers above and below. ....	89
Figure 9-5: Example of target quality of microsection of innerlayer (top) and knee of the hole (bottom), as-polished (left) and after micro-etch (right). ....	103
Figure 9-6: Examples of inadequate quality of microsection showing in the top image inadequate polishing, leaving scratches on surface, in the middle image over-etched sample and in the bottom image inadequate lighting, revealing no detail on metallisation, nor on laminate by transparency.....	104
Figure 9-7: Examples of barrel cracks after IST testing showing a nominal crack size (left) and a large crack filled with SnPb (right) .....	112
Figure 9-8: THB test pattern .....	119
Figure 9-9: Build-up for THB test vehicle .....	120
Figure 9-10: Insulation resistance during THB Ambient (until sample nr 1000) and THB ECM showing continuous breach of insulation on 4 patterns in the lower graph. The top graph shows stable insulation. ....	122
Figure 9-11: Horizontal microsection showing fibre contamination on tracks in prepreg resin causing breach of insulation. ....	123
Figure 9-12: Lay-out of CAF pattern .....	126
Figure 9-13: Schematic for CAF growth.....	126
Figure 10-1: Annular ring internal .....	133
Figure 10-2 Annular ring external .....	134

Figure 10-3: Copper foil thickness .....	135
Figure 10-4: Three measurements of copper plating thickness at locations that are at 25 %, 50 % and 7 % of the height of the hole.....	137
Figure 10-5: Measurement “average on resin” is performed on zone A. Measurement “on any local thin areas on resin or glass” is performed on Zone B .....	137
Figure 10-6: Glass fibre protrusion in case of negative etchback (left) and positive etchback (right) .....	139
Figure 10-7: Example of negative etchback (left) and approximately neutral etchback (right) .....	139
Figure 10-8: Wicking is measured from resin of hole wall (red arrows). In case it exceeds the annular ring, the insulation distance to adjacent circuitry (blue arrow) can be reduced. ....	140
Figure 10-9: Example of wicking.....	140
Figure 10-10: wrap target condition .....	141
Figure 10-11: Wrap thickness below requirement, not acceptable .....	141
Figure 10-12: Projected-peak-to-peak insulation .....	142
Figure 10-13: Example of glass compression .....	142
Figure 10-14 Microvia insulation.....	143
Figure 10-15 Penetration of capture pad for $\mu$ via, not acceptable.....	143
Figure 10-16 Microvia aspect ratio, $X \geq Z$ .....	144
Figure 10-17 Dimple in microvia .....	144
Figure 10-18 ICD on capture pad .....	144
Figure 10-19 Microvia plating, target condition .....	145
Figure 10-20 Example of void in microvia plating.....	145
Figure 10-21: Tin-lead thickness in PTH schematic (left) and a typical microsection (right) .....	147
Figure 10-22: Tin-lead thickness on PTH corner – target thickness (left), coverage of less than 1 $\mu$ m (middle), absence of SnPb on IMC (right).....	147
Figure 10-23: Tin-lead thickness on pad.....	147
Figure 10-24: Undercut.....	150
Figure 10-25: Overhang of electrolytic Au .....	151
Figure 10-26: Example of dimensional verification of rigid-flex interface.....	152
Figure 10-27: examples of acceptable voids.....	155
Figure 10-28: examples of unacceptable voids.....	155
Figure 10-29: example of acceptable thin line separation .....	156
Figure 10-30: example of non-acceptable bulging .....	156
<b>Figure 10-31: Example of dimple on blind via .....</b>	<b>157</b>
Figure 10-32: Example of bump on blind via.....	157
Figure 10-33: Example of voids – top image shows etch-out and bottom image shows an encapsulated void or inclusion.....	160

Figure 10-34: Skip plating on flex laminate as-polished (top) and after micro-etch (bottom).....	160
Figure 10-35: Skip plating on glass fibres.....	160
Figure 10-36 Schematic of wedge voids.....	162
Figure 10-37 Example of wedge voids.....	162
Figure 10-38: Example of resin void .....	163
Figure 10-39: Example of delamination .....	164
Figure 10-40: Pad lift schematic .....	166
Figure 10-41: Examples of pad lift cracks. The right image is unacceptable because cracks continue until the hole wall .....	166
Figure 10-42: Acceptable (green) and non-acceptable (red) dielectric cracks.....	168
Figure 10-43: Examples of laminate cracks .....	168
Figure 10-44: Example of C foil separation as-polished and after micro-etch .....	171
Figure 10-45: Example of interface line between plated copper layers on a non-etched microsection.....	171
Figure 10-46: Interconnect after stress, target condition, after microetch (top) and as-polished (bottom) .....	173
Figure 10-47: Examples of ICD .....	173
Figure 10-48 Example of smear .....	174
Figure 10-49: Example of hole wall pull away - showing separation of copper in a straight line (left) or slightly bulging outward (right).....	176
Figure 10-50: Example of resin recession - showing concave retraction of epoxy resin.....	176
Figure 10-51: Target condition.....	178
Figure 10-52: Acceptable nail heading .....	178
Figure 10-53:Unacceptable nail heading, exceeding 50 % of innerlayer copper thickness.....	178
Figure 10-54: Examples of CIC connection, target condition (left), nailheading (middle), separation to CIC (right).....	179
Figure 10-55: Examples of swirl (left and middle) and demarcation line (right). In the middle picture the difference between no-flow prepreg (top) and laminate (bottom) is noticeable. ....	180
Figure 10-56: Example of metallic contamination in laminate .....	181
Figure 10-57: Acceptable adhesion between coverlay and prepreg.....	182
Figure 10-58: Delamination between coverlay and prepreg.....	182
Figure 10-59 Example of voids in acrylic adhesive in rigid-to-flex interface.....	183
Figure 10-60: Example of adhesive filet recession into rigid section as observed in microsection.....	184
Figure 10-61: Conductor width .....	188
Figure 10-62: Conductor spacing .....	190
Figure 10-63: Example of lifted land .....	192
Figure 10-64: Example of visible copper on top surface (left) and on side of track (right) ...	192

Figure 10-65: Example of measling .....	193
Figure 10-66: Examples of crazing .....	193
Figure 10-67: Examples of contamination and inhomogeneity.....	194
Figure 10-68: Example of scratches on conductors and dielectric .....	196
Figure 10-69: Haloing at edge .....	198
Figure 10-70: Haloing from non-plated hole to footprint for stiffener .....	198
Figure 10-71: Granular aspect.....	199
Figure 10-72: Dewetting .....	199
Figure 10-73: Example of unclear marking .....	200
Figure 10-74: Example of resin squeeze out .....	201
Figure 10-75: Example of adhesive filet recession into rigid section as observed in visual inspection.....	201
Figure 10-76: Examples of fibre protrusion .....	202
Figure 10-77: Example of acceptable incidental haloing $\leq 1$ mm into rigid section.....	203
Figure 10-78: Example of an acceptable superficial scratch .....	205
Figure 10-79: Examples of non-acceptable cut and blister, evident by a sharp indentation .....	205
Figure 10-80: Examples of burrs on edge of flex .....	205
Figure 10-81: Misregistration of top and bottom coverlay .....	209
Figure 10-82: Misregistration of hole in coverlay to the conductor .....	209
Figure 10-83: Examples of white spot configurations and black spot contamination .....	212
Figure 10-84: Examples of fibre contamination.....	212
Figure 10-85: Examples of SnPb infiltration on sculptured pad (left) and on tracks (right) .....	213
Figure 10-86: Bare copper on fingers .....	214
Figure 10-87: Misregistration of pads .....	215
Figure 10-88: Hole misregistration causing reduced annular ring .....	216
Figure 10-89: Schematic of conductor width and spacing and local defects .....	218
Figure 10-90: Examples of nick near pad, nick on conductor, overetching reducing thickness of conductor, nick on finger, pinhole and local reduced track width (left to right).....	219
Figure 10-91: Examples of insufficient spacing between conductors, copper residue between pads, copper residue to edge of flex, bump on conductor (left to right).....	219
Figure 10-92: Adhesive in plated holes.....	220
Figure 10-93: Example of adhesive in plated holes .....	220
Figure 10-94: SnPb coverage on pads .....	222
Figure 10-95: Pad diameter reduction due to local coverage by coverlay or resin squeeze out .....	222
Figure 10-96: Copper wrinkle .....	223



Figure 10-97: Tear in hole and edge of coverlay .....	224
Figure 10-98: Burrs on holes .....	224
Figure 10-99: Nick on edge of coverlay .....	224
Figure 10-100: Coverlay scratch – Non acceptable .....	225
Figure 10-101: Acceptable aspect of finger after bending .....	226
Figure 10-102: Unacceptable aspect of finger after bending .....	226
Figure 10-103: Cross section of hole: Copper conductor shown .....	229
Figure 10-104: Calculation of remaining insulation distance .....	233

## **Tables**

Table B-1 : Example of a declaration of conformance .....	242
Table B-2 : Example of a lab report for visual inspection of PCBs for qualitative aspects ...	243
Table B-3 : Example of a lab report for visual inspection of PCBs for dimensional verification.....	244
Table B-4 : Example of a Lab report for microsection of coupons for qualitative aspects....	245
Table B-5 : Example of a lab report for microsection of coupons for dimensional verification.....	246
Table B-6 : Example of a build-up report .....	248
Table B-7 : Example of a lab report for additional tests.....	249
Table G-1 : Example of a PCB approval sheet part 1 .....	258
Table G-2 : Example of a PCB approval sheet part 2 .....	259